

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:	)	Before the Examiner
	)	
Michael T. Meyer	)	Group Art Unit
	)	
Serial No. 10/635,101	)	
	)	
Filed: August 6, 2003	)	
	)	
APPARATUS FOR HEAT TRANSFER	)	
AND CRITICAL HEAT FLUX	)	
ENHANCEMENT	)	October 6, 2003

INFORMATION DISCLOSURE STATEMENT

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P.O. Box 1450  
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The references are listed on the attached Form 1449.

Copies of cited items are enclosed herewith.

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Clifford W. Browning  
Name of Registered Representative

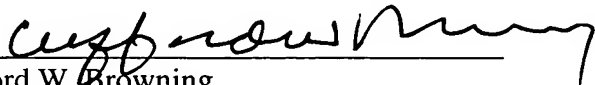
  
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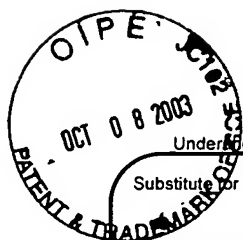
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Respectfully submitted

By:   
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**Complete if Known****INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Application Number	10/635,101
Filing Date	August 6, 2003
First Named Inventor	Michael T. Meyer
Art Unit	
Examiner Name	
Attorney Docket Number	16380-4
Sheet 1 of 3	

**NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
		BOWERS, M.B. et al., High flux boiling in low flow rate, low pressure mini-channel and micro-channel heat sinks. Int. J. Heat Mass Transfer, Vol. 37, No. 2, pp.321-332, 1994, Great Britain.	
		BOWERS, M.B. et al., Two-Phase Electronic Cooling Using Mini-Channel and Micro-Channel Heat Sinks: Part 1 - Design Criteria and Heat Diffusion Constraints. Transactions of the ASME, Vol. 116, pp. 290-297, December 1994.	
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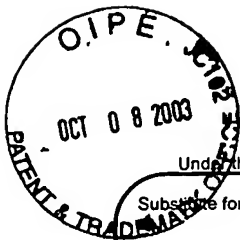
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Sheet	2	of	3
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		Maddox, D.E. et al., Single- and Two-Phase Convective Heat Transfer from Smooth and Enhanced Microelectric Heat Sources in a Rectangular Channel. Journal of Heat Transfer, Vol. 111, pp. 1045-1052, November 1989.	/
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		MUDAWAR, I. et al., Critical heat flux from a simulated chip to a confined rectangular impinging jet of dielectric liquid. Int. J. Heat Mass Transfer, Vol. 34, No. 6, pp. 1465-1479, 1991, Great Britain.	/
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		PENG, X. F. et al., Forced convection and flow boiling heat transfer for liquid flowing through microchannels. Int. J. Heat Mass Transfer, Vol. 36, No. 14, pp. 3421-3427, 1993, Great Britain.	/

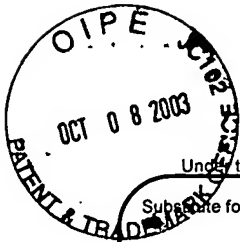
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		Advances in Thermal Modeling of Electronic Components and Systems, Vol. 2, ASME Press Series, New York, 1990.	/
		Ravigururajan, T.S., Impact of Channel Geometry on Two-Phase Flow Heat Transfer Characteristics of Refrigerants in Microchannel Heat Exchangers. Journal of Heat Transfer, Vol. 120, pp. 485-491, May 1998.	/
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		YAN, Yi-Yie et al., Evaporation heat transfer and pressure drop of refrigerant R-134a in a small pipe. Int. J. Heat Mass Transfer, Vol. 41, pp. 4183-4194, Pergamon Press 1998.	

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